

AMENDMENTS TO THE CLAIMS

1. - 6. (Cancelled)

7. (Currently Amended) A ~~disk drive~~ suspension comprising:

a suspension bonding pad for electrically bonding a magnetic head terminal, wherein said bonding pad includes a metal pad having a bonding substance applied as a surface finishing material, the surface finishing material being heat treated prior to bonding to a surface; and
a slider bonding pad initially without bonding substance coupled to said suspension such that the bonding substance on said suspension bonding pad is reflowed so as to electrically couple the suspension bonding pad and the slider bonding pad.

8. (Currently Amended) The ~~disk drive~~ as claim in claim 7, wherein said bonding substance is solder.

9. (Currently Amended) The ~~disk drive~~ as claim in claim 7, wherein said bonding substance is a conductive polymer.

10. (Currently Amended) The ~~disk drive~~ as claim in claim 7, wherein said bonding substance is an adhesive.

11. (Currently Amended) The ~~disk drive~~ as claim in claim 7, wherein said bonding substance is a film.

12. (Currently Amended) The ~~disk drive~~ as claim in claim 8, wherein a bump height for the solder is approximately 50-300 μm , and a bump diameter for the solder is less than 180 μm .
